MADS-011030-14280W

Schottky Zero Bias Detector Diode

Rev. V1

MACOM Technology Solutions Inc. (MACOM) and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice.

Visit www.macom.com for additional data sheets and product information.

For further information and support please visit: https://www.macom.com/support

Features
- P-Type Schottky Diode
- Low Slope Resistance, 6.5 Ω
- Can be used Without External DC Bias
- Large Bondable Contact
- Can be Mounted with Solder or Conductive Epoxy
- RoHS Compliant*

Description
The MADS-011030-14280W is a zero bias detector diode (ZBD). This diode is a bondable die suitable for use in microstrip or stripline detector circuits. These chips can be used in automatic assembly processes due to their 2.5 x 10 mil rectangular gold contact and sturdy construction.

Ordering Information

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Package</th>
</tr>
</thead>
<tbody>
<tr>
<td>MADS-011030-14280W</td>
<td>Waffle Pack</td>
</tr>
</tbody>
</table>


Functional Schematic

Chip Outline

1. Topside metal (cathode contact) thickness: 10 microns Au (Typical)
2. Backside metal (anode contact) thickness: 0.1 micron Au (Typical)
Absolute Maximum Ratings

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Absolute Maximum</th>
</tr>
</thead>
<tbody>
<tr>
<td>Reverse Voltage @ 25°C</td>
<td>2.5 Volts</td>
</tr>
<tr>
<td>Operating Temperature</td>
<td>-55°C to +125°C</td>
</tr>
<tr>
<td>Storage Temperature</td>
<td>-55°C to +150°C</td>
</tr>
</tbody>
</table>

Handling Procedures

Please observe the following precautions to avoid damage:

Static Sensitivity

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these HBM Class 0 devices.

Die Handling and Mounting Information

Handling: All semiconductor chips should be handled with care in order to avoid damage or contamination from perspiration, salts, and skin oils. For individual die, the use of plastic tipped tweezers or vacuum pick up tools is strongly recommended. Bulk handling should ensure that abrasion and mechanical shock are minimized.

Die Attach: The die have Ti-Pt-Au back metal and gold plated contact metal. Die can be mounted with a gold-tin, eutectic solder preform or conductive silver epoxy.

Eutectic Die Attachment Using Hot Gas Die Bonder: An 80/20, gold tin eutectic solder perform is recommended with a work surface temperature of 255°C and a tool tip temperature of 220°C. When the hot gas is applied, the temperature at the tool tip should be approximately 290°C.

Eutectic Die Attachment Using Reflow Oven: See Application Note M541, “Bonding and Handling Procedures for Chip Diode Devices”.

Epoxy Die Attachment: A thin, controlled amount of electrically conductive silver epoxy should be applied at approximately a 1-2 mils thickness to minimize ohmic and thermal resistances. A thin epoxy fillet should be visible around the perimeter of the chip after placement to ensure full area coverage. Cure conductive epoxy per manufacturer’s schedule.

Wire Bonding: 0.001” diameter gold wire is recommended with a stage temperature of 150°C and minimal force. Ultrasonic energy should be adjusted to the minimum required. Automatic ball bonding can also be used.